



CYPRESS

CY7C332

Registered Combinatorial EPLD

Features

- 12 I/O macrocells each having:
 - Registered, latched, or transparent array input
 - A choice of two clock sources
 - Global or local output enable (OE)
 - Up to 19 product terms (PTs) per output
 - Product term (PT) output polarity control
- 192 product terms with variable distribution to macrocells
 - An average of 14 PTs per macrocell sum node
- Two clock inputs with configurable polarity control

- 13 input macrocells, each having:
 - Complementary input
 - Register, latch, or transparent access
 - Two clock sources
- 15 ns t_{PD} max.
- Low power
 - 120 mA typical I_{CC} quiescent
 - 180 mA max.
 - Power-saving "Miser Bit" feature
- Security fuse
- 28-pin slim-line package; also available in 28-pin PLCC
- UV-erasable and reprogrammable
- Programming and operation 100% testable

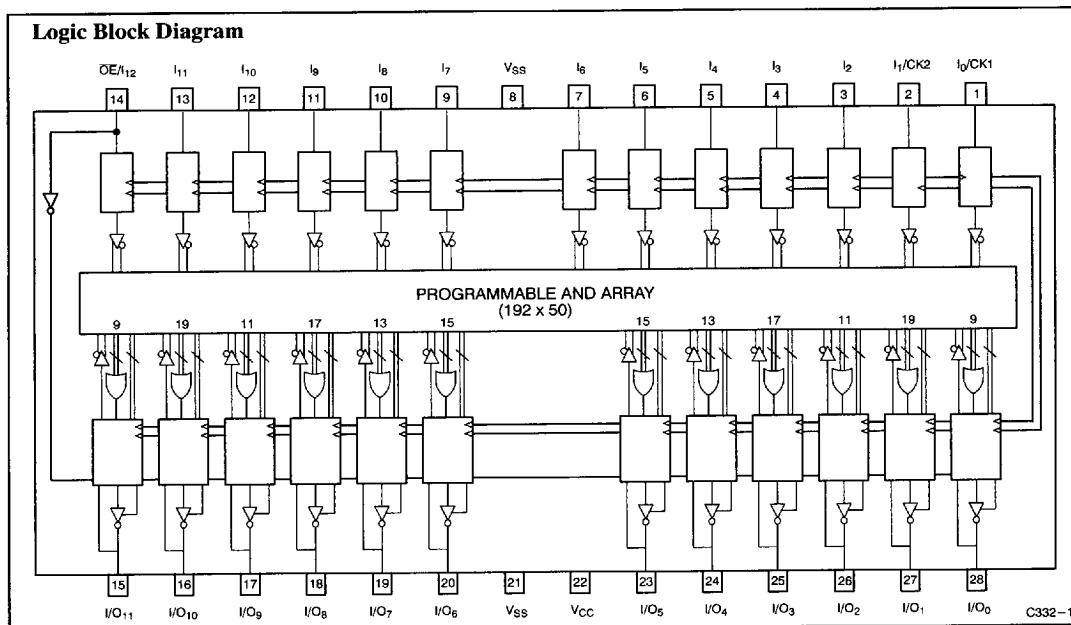
Functional Description

The CY7C332 is a versatile combinatorial PLD with I/O registers on-board. There are 25 array inputs; each has a macrocell that may be configured as a register, latch, or simple buffer. Outputs have polarity and three-state control product terms. The allocation of product terms to I/O macrocells is varied so that functions of up to 19 product terms can be accommodated.

I/O Resources

Pins 1 through 7 and 9 through 14 function as dedicated array inputs. Pins 1 and 2 function as input clocks as well as normal inputs. Pin 14 functions as a global output enable as well as a normal input.

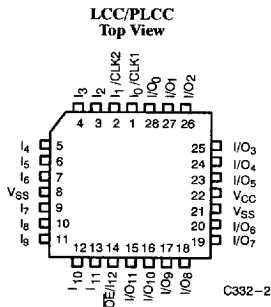
Logic Block Diagram



Selection Guide

Generic Part Number	I_{CC1} (mA)		t_{CO}/t_{PD} (ns)		t_{IS} (ns)	
	Commercial	Military	Commercial	Military	Commercial	Military
7C332-15	130		18/15		3	
7C332-20	120	160	20	23/20	3	4
7C332-25	120	150	25	25	3	4
7C332-30		150		30		4

Pin Configuration



I/O Resources (continued)

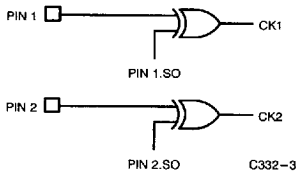
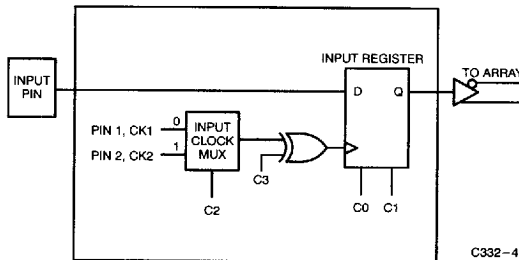


Figure 1. CK1 and CK2

Pins 15 through 20 and 23 through 28 are connected to I/O macrocells and may be combinational outputs as well as registered or direct inputs.

Input Macrocell



C3	C2	C1	C0	Input Register Option
X	X	0	0	Combinational
X	X	0	1	Illegal
0	0	1	1	Registered, CLK1, Rising Edge
0	1	1	1	Registered, CLK2, Rising Edge
1	0	1	1	Registered, CLK1, Falling Edge
1	1	1	1	Registered, CLK2, Falling Edge
0	0	1	0	Latched, CLK1, LOW Transparent
0	1	1	0	Latched, CLK2, LOW Transparent
1	0	1	0	Latched, CLK1, HIGH Transparent
1	1	1	0	Latched, CLK2, HIGH Transparent

Figure 2. Input Macrocell

There are 13 input macrocells, corresponding to pins 1 through 7 and 9 through 14. Each macrocell has a clock that is selected to come from either pin 1 or pin 2 by configuration bit C2. Pins 1 and 2 are clocks as well as normal inputs. There is no C2 configuration bit for either of these two input macrocells. Macrocells connected to pins 1 and 2 do not have a clock choice, but each has a clock coming from the other pin.

Each input macrocell can be configured as a register, latch, or simple buffer (transparent path) to the product term array. For a register the configuration bit, C0, is 1 (programmed) and C1 is 1. For a latch, C0 is 0 and C1 is 1. If both C0 and C1 are 0 (unprogrammed), then the macrocell is completely transparent.

Configuration bit C3 determines the clock edge on which the register is triggered or the polarity for which the latch is asserted. This clock polarity can be programmed independently for each input register. These confirmation options are available on all inputs, including those in the I/O macrocell.

If C3 is 0 (unprogrammed), the clock will be rising-edge triggered (register mode) or HIGH asserted (latch mode). If C3 is 1 (programmed), the clock will be falling-edge triggered (register mode) or LOW asserted (latch mode).

I/O Macrocell

There are 12 I/O macrocells corresponding to pins 15 through 20 and 23 through 28. Each macrocell has a three-state output control and XOR product term to dynamically control polarity, and a configurable feedback path.

For each I/O macrocell, the three-state control for the output may be configured two ways. If the configuration bit, C4, is a 1 (programmed), then the global OE signal is selected. Otherwise, the OE product term is used.

For each I/O macrocell, the input/feedback path may be configured as a register, latch, or shunt. There are two configuration bits per I/O macrocell that configure the feedback path. These are programmed in the same way as for the input macrocells.

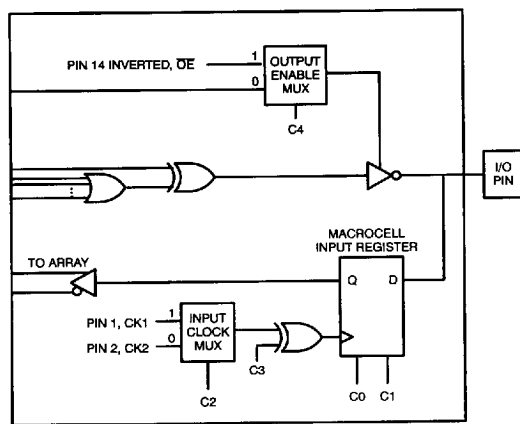
For each I/O macrocell, the input register clock (or Latch Enable) that is used for the input/feedback path may be selected as pin 1 (select bit, C2, not programmed) or pin 2 (select bit, C2, programmed).

Array Allocation to Output Macrocell

The number of product terms in each output macrocell sum is position dependent. Table 1 summarizes the allocation.

Table 1. Product Term Allocation in Output Macrocell

Macrocell	Pin Number	Product Term
0	28	9
1	27	19
2	26	11
3	25	17
4	24	13
5	23	15
6	20	15
7	19	13
8	18	17
9	17	11
10	16	19
11	15	9


Figure 3. I/O Macrocell

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-55°C to +125°C
Supply Voltage to Ground Potential (Pin 22 to Pins 8 and 21)	-0.5V to +7.0V
DC Input Voltage	-3.0V to +7.0V
Output Current into Outputs (LOW)	12 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	>200 mA
DC Programming Voltage	13.0V

Operating Range

Range	Ambient Temperature	V _{CC}
Commercial	0°C to +75°C	5V ± 10%
Military ^[1]	-55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min., V _{IN} = V _{IH} or V _{IL} I _{OH} = -3.2 mA Commercial I _{OH} = -2 mA Military	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., V _{IN} = V _{IH} or V _{IL} I _{OL} = 12 mA Commercial I _{OL} = 8 mA Military		0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed HIGH Input, all Inputs ^[2]	2.2		V
V _{IL}	Input LOW Voltage	Guaranteed LOW Input, all Inputs ^[2]		0.8	V
I _{IX}	Input Leakage Current	V _{SS} < V _{IN} < V _{CC} , V _{CC} = Max.	-10	+10	μA
I _{OZ}	Output Leakage Current	V _{CC} = Max., V _{SS} < V _{OUT} < V _{CC} .	-40	+40	μA
I _{SC}	Output Short Circuit Current	V _{CC} = Max., V _{OUT} = 0.5V ^[3]	-30	-90	mA
I _{CC1}	Standby Power Supply Current	V _{CC} = Max., V _{IN} = GND Outputs Open	Commercial Commercial -15 Military Military -20	120 130 150 160	mA
I _{CC2}	Power Supply Current at Frequency ^[4,5]	V _{CC} = Max. Outputs Disabled (In High Z State) Device Operating at f _{MAX} External (f _{MAX1})	Commercial Military	180 200	mA

Notes:

1. T_A is the "instant on" case temperature.
2. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
3. Not more than one output should be tested at a time. Duration of the short circuit should not be more than one second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.

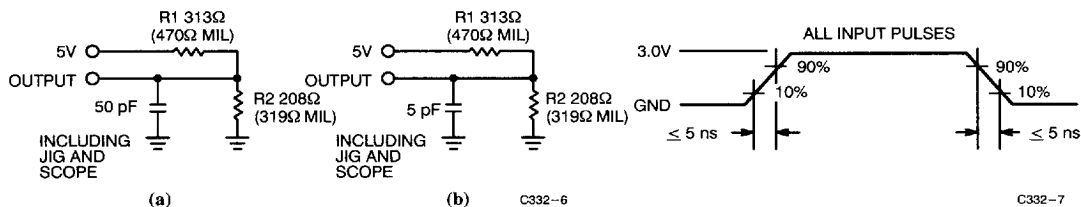
4. Tested by periodic sampling of production product.
5. Refer to Figure 4 configuration 2.

Capacitance^[6]

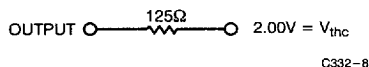
Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	$V_{IN} = 2.0V$ at $f = 1\text{ MHz}$,	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 2.0V$ at $f = 1\text{ MHz}$,	10	pF

Note:

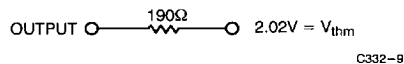
6. Tested initially and after any design or process changes that may affect these parameters.

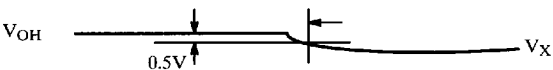
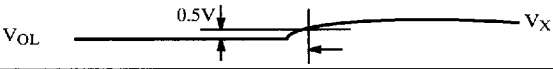
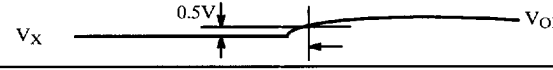
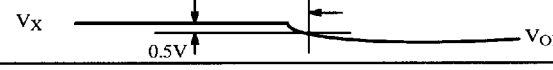
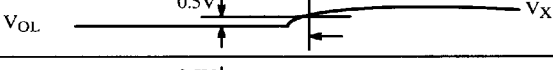
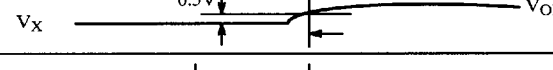
AC Test Loads and Waveforms


Equivalent to: THÉVENIN EQUIVALENT (Commercial)



Equivalent to: THÉVENIN EQUIVALENT (Military)



Parameter	V_X	Output Waveform—Measurement Level
$t_{PXZ}(-)$	1.5V	 C332-10
$t_{PXZ}(+)$	2.6V	 C332-11
$t_{PZX}(+)$	V_{thc}	 C332-12
$t_{PZX}(-)$	V_{thc}	 C332-13
$t_{ER}(-)$	1.5V	 C332-14
$t_{ER}(+)$	2.6V	 C332-15
$t_{EA}(+)$	V_{thc}	 C332-16
$t_{EA}(-)$	V_{thc}	 C332-17

(c) Test Waveforms and Measurement Levels

Switching Characteristics Over the Operating Range^[2]

Parameter	Description	Commercial						Military						Unit
		−15 ^[7]		−20		−25		−20 ^[7]		−25		−30		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	Input to Output Propagation Delay ^[8]		15		20		25		20		25		30	ns
t _{ICO}	Input Register Clock to Output Delay ^[9]		18		20		25		23		25		30	ns
t _{IS}	Input or Feedback Set-Up Time to Input Register Clock ^[9]	3		3		3		4		4		4		ns
t _{IH}	Input Register Hold Time ^[9]	3		3		3		4		4		4		ns
t _{EA}	Input to Output Enable Delay ^[10, 11]		20		20		25		25		25		30	ns
t _{ER}	Input to Output Disable Delay ^[10, 11]		20		20		25		25		25		30	ns
t _{PZX}	Pin 14 Enable to Output Enable Delay ^[8, 12]		15		15		20		20		20		25	ns
t _{PXZ}	Pin 14 Disable to Output Disable Delay ^[8, 12]		15		15		20		20		20		25	ns
t _{WH}	Input Clock Width High ^[4, 9]	9		10		10		10		10		12		ns
t _{WL}	Input Clock Width Low ^[4, 9]	9		10		10		10		10		12		ns
t _{IOH}	Output Data Stable Time from Input Register Clock Input ^[7, 9]	3		3		3		3		4		4		ns
t _{IOH} − t _{IH}	Output Data Stable Time This Device Minus I/P Reg Hold Time Same Device ^[7, 13, 14]	0		0		0		0		0		0		ns
t _{IOH} − t _{IH} 33x	Output Data Stable Time Minus I/P Reg Hold Time 7C330 and 7C332 Device ^[9, 15]	0		0		0		0		0		0		ns
t _{PE}	External Clock Period (t _{ICO} + t _{IS}) ^[9]	21		23		28		27		29		34		ns
f _{MAX1}	Maximum External Operating Frequency (1/(t _{ICO} + t _{IS})) ^[9]	47.6		43.4		35.7		37		34.4		29.4		MHz
f _{MAX}	Maximum Frequency Data Path ^[9]	55.5		50.0		40.0		50.0		40.0		33.3		MHz

Notes:

7. Preliminary specifications.

8. Refer to Figure 4 configuration 1.

9. Refer to Figure 4 configuration 2.

10. Part (a) of AC Test Loads and Waveforms is used for all parameters except t_{EA}, t_{ER}, t_{PZX}, and t_{PXZ}, which use part (b). Part (c) shows test waveform and measurement reference levels.

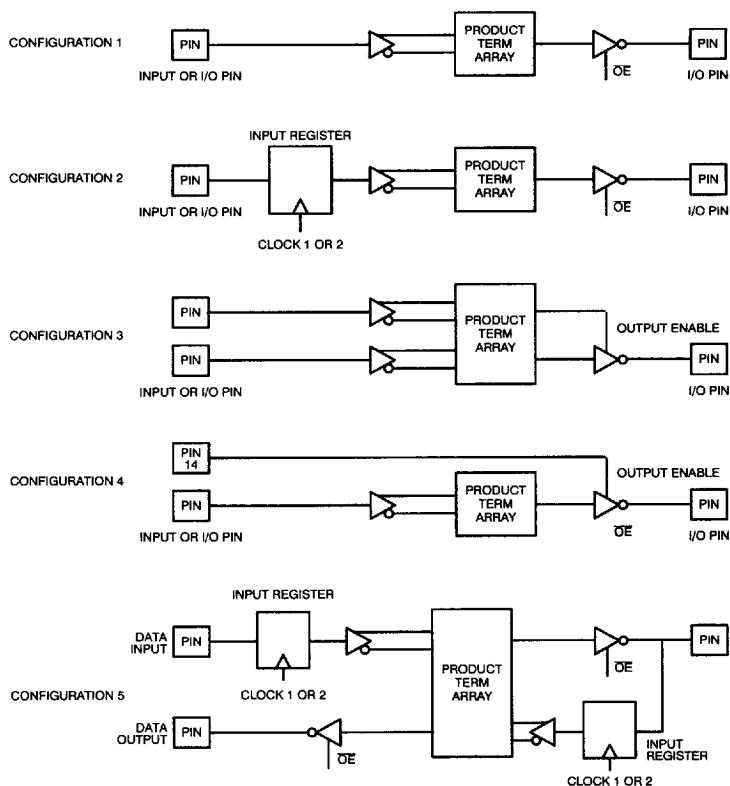
11. Refer to Figure 4 configuration 3.

12. Refer to Figure 4 configuration 4.

13. Refer to Figure 4 configuration 5.

14. This specification is intended to guarantee that configuration 5 of Figure 4 with input registered feedback can be operated with all input register clocks controlled by the same source. These parameters are tested by periodic sampling of production product.

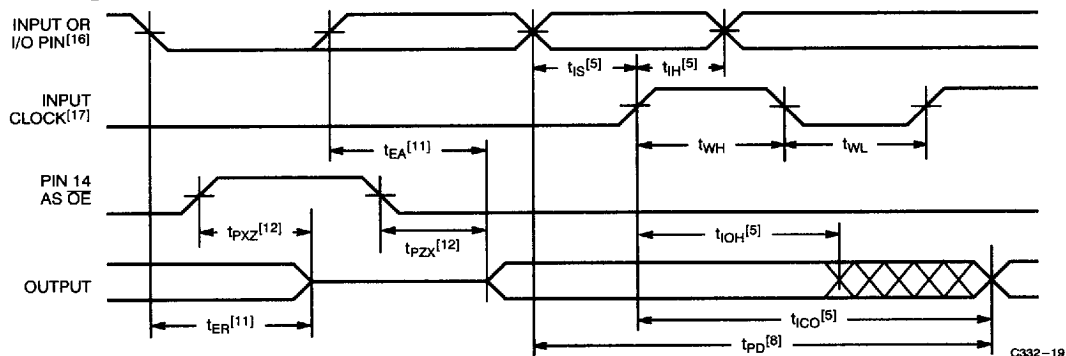
15. This specification is intended to guarantee interface compatibility of the other members of the CY7C330 family with the CY7C332. This specification is met for the devices noted operating at the same ambient temperature and at the same power supply voltage. These parameters are tested periodically by sampling of production product.



C332-18

Figure 4. Timing Configurations

Switching Waveforms

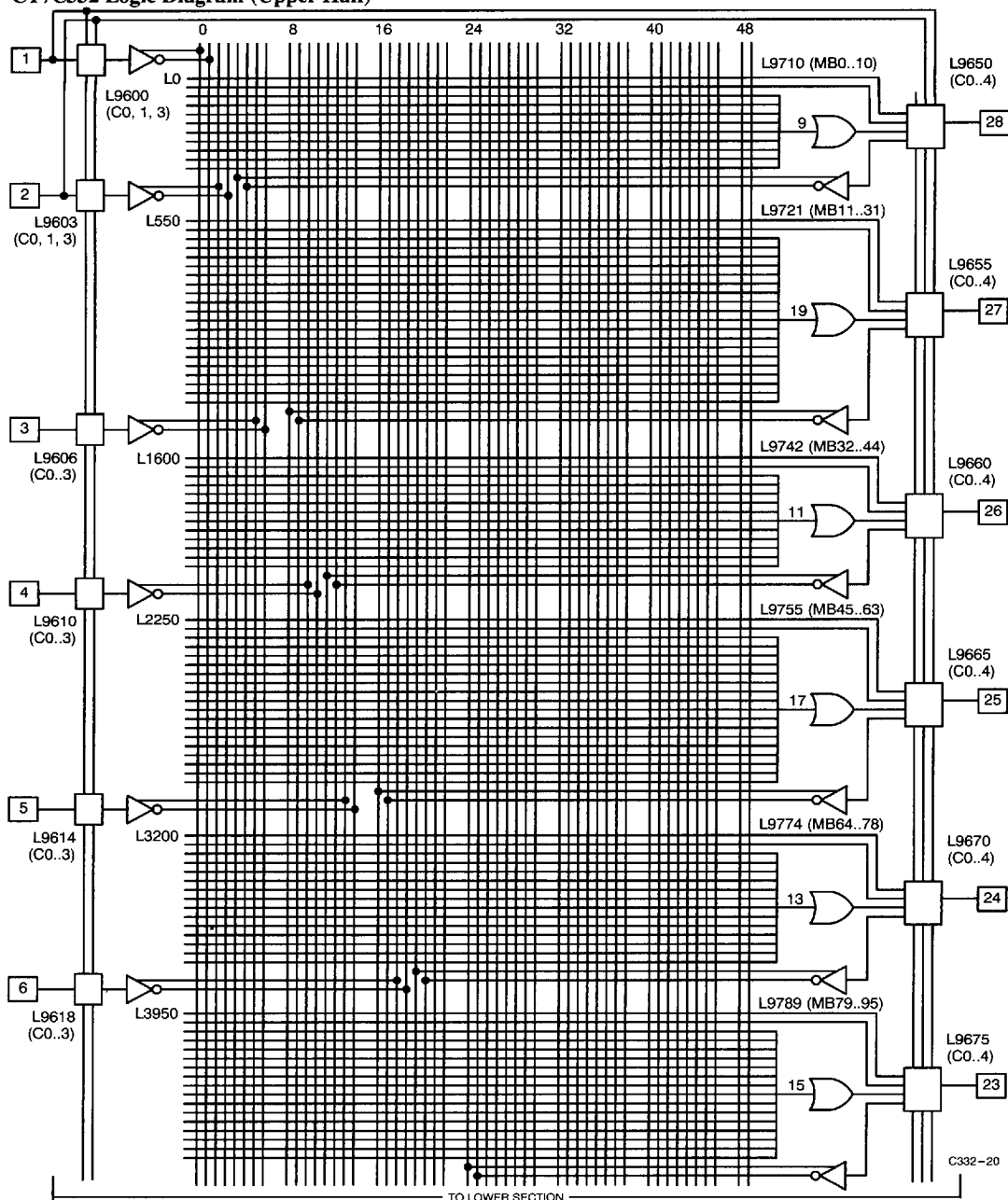


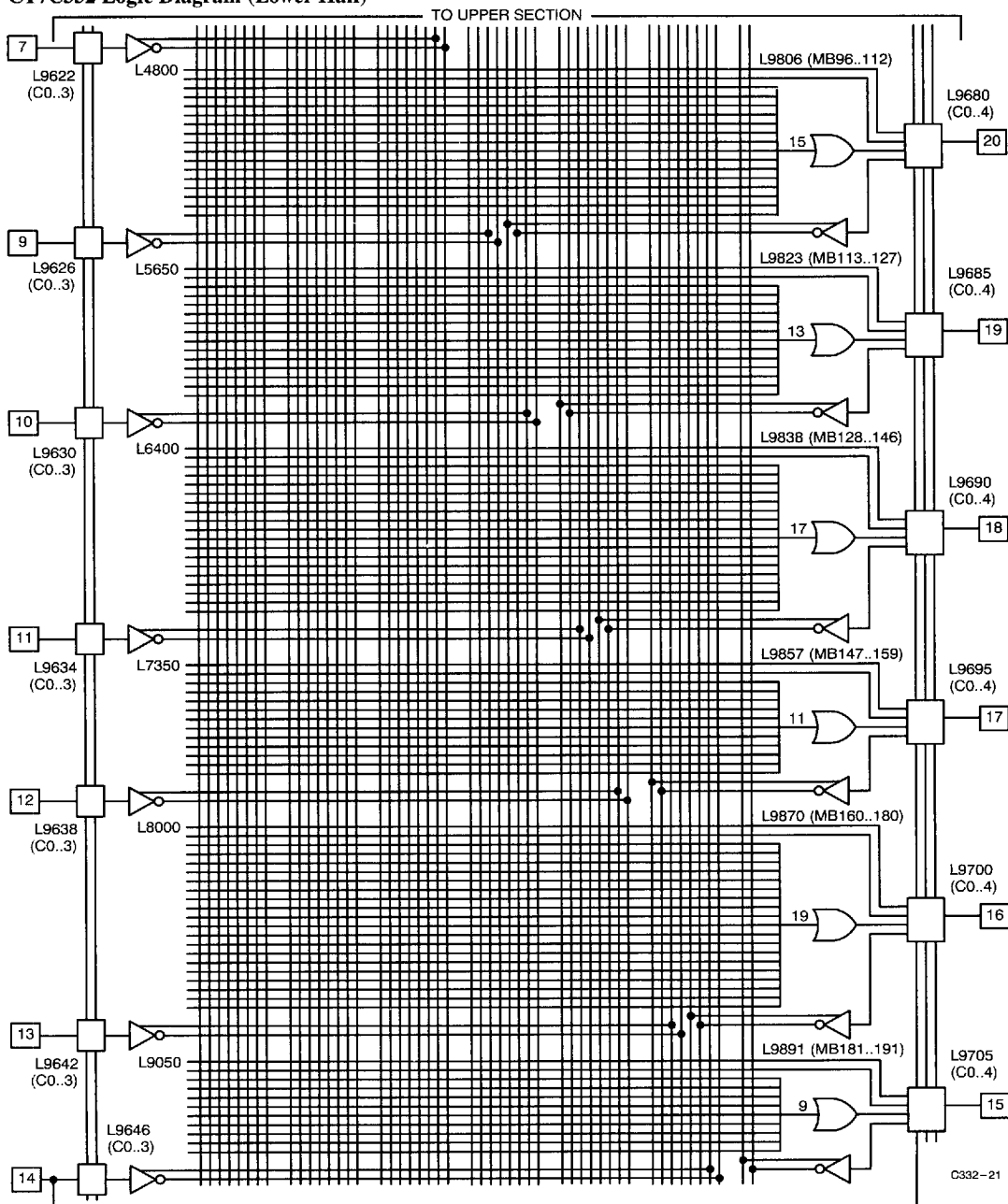
C332-19

Notes:

16. Because OE can be controlled by the $\overline{\text{OE}}$ product term, input signal polarity for control of OE can be of either polarity. Internally the product term $\overline{\text{OE}}$ signal is active HIGH.

17. Since the input register clock polarity is programmable, the input clock may be rising- or falling-edge triggered.

CY7C332 Logic Diagram (Upper Half)


CY7C332 Logic Diagram (Lower Half)


Ordering Information

I_{CC1} (max)	t_{CO}/t_{PD} (ns)	t_{IS} (ns)	t_{IH} (ns)	Ordering Code	Package Name	Package Type	Operating Range
120	18/15	3	3	CY7C332-15HC	H64	28-Pin Windowed Leaded Chip Carrier	Commercial
				CY7C332-15JC	J64	28-Lead Plastic Leaded Chip Carrier	
				CY7C332-15PC	P21	28-Lead (300-Mil) Molded DIP	
				CY7C332-15WC	W22	28-Lead (300-Mil) Windowed CerDIP	
120	20	3	3	CY7C332-20HC	H64	28-Pin Windowed Leaded Chip Carrier	Commercial
				CY7C332-20JC	J64	28-Lead Plastic Leaded Chip Carrier	
				CY7C332-20PC	P21	28-Lead (300-Mil) Molded DIP	
				CY7C332-20WC	W22	28-Lead (300-Mil) Windowed CerDIP	
160	23/20	4	4	CY7C332-20DMB	D22	28-Lead (300-Mil) CerDIP	Military
				CY7C332-20HMB	H64	28-Pin Windowed Leaded Chip Carrier	
				CY7C332-20LMB	L64	28-Square Leadless Chip Carrier	
				CY7C332-20TMB	T74	28-Lead Windowed Cerpack	
				CY7C332-20WMB	W22	28-Lead (300-Mil) Windowed CerDIP	
120	25	3	3	CY7C332-25HC	H64	28-Pin Windowed Leaded Chip Carrier	Commercial
				CY7C332-25JC	J64	28-Lead Plastic Leaded Chip Carrier	
				CY7C332-25PC	P21	28-Lead (300-Mil) Molded DIP	
				CY7C332-25WC	W22	28-Lead (300-Mil) Windowed CerDIP	
150	25	4	4	CY7C332-25DMB	D22	28-Lead (300-Mil) CerDIP	Military
				CY7C332-25HMB	H64	28-Pin Windowed Leaded Chip Carrier	
				CY7C332-25LMB	L64	28-Square Leadless Chip Carrier	
				CY7C332-25TMB	T74	28-Lead Windowed Cerpack	
				CY7C332-25WMB	W22	28-Lead (300-Mil) Windowed CerDIP	
150	30	4	4	CY7C332-30DMB	D22	28-Lead (300-Mil) CerDIP	Military
				CY7C332-30HMB	H64	28-Pin Windowed Leaded Chip Carrier	
				CY7C332-30LMB	L64	28-Square Leadless Chip Carrier	
				CY7C332-30TMB	T74	28-Lead Windowed Cerpack	
				CY7C332-30WMB	W22	28-Lead (300-Mil) Windowed CerDIP	

MILITARY SPECIFICATIONS
Group A Subgroup Testing**DC Characteristics**

Parameter	Subgroups
V_{OH}	1, 2, 3
V_{OL}	1, 2, 3
V_{IH}	1, 2, 3
V_{IL}	1, 2, 3
I_{IX}	1, 2, 3
I_{OZ}	1, 2, 3
I_{CC1}	1, 2, 3

2

Switching Characteristics

Parameter	Subgroups
t_{IS}	9, 10, 11
t_{IH}	9, 10, 11
t_{ICO}	9, 10, 11
t_{PD}	9, 10, 11
t_{PXZ}	9, 10, 11
t_{PZX}	9, 10, 11
t_{ER}	9, 10, 11
t_{EA}	9, 10, 11

Document #: 38-00067-D